



Material Content Data Sheet



Sales Product Name				BSC019N02KS G		Issued		25. September 2017	
MA#				MA000434298					
Package				PG-TDSON-8-1		Weight*		122.69 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.248	4.28	4.28	42774	42774	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		308		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		92		
	non noble metal	copper	7440-50-8	37.762	30.79	30.83	307790	308190	
wire	non noble metal	copper	7440-50-8	0.024	0.02	0.02	192	192	
encapsulation	organic material	carbon black	1333-86-4	0.078	0.06		637		
	plastics	epoxy resin	-	5.551	4.52		45245		
	inorganic material	silicondioxide	60676-86-0	33.462	27.27	31.85	272745	318627	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.18	1.18	11832	11832	
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1349	1349	
solder	noble metal	silver	7440-22-4	0.099	0.08		805		
	non noble metal	tin	7440-31-5	0.079	0.06		644		
	non noble metal	lead	7439-92-1	3.773	3.08	3.22	30756	32205	
CLIP plating	noble metal	silver	7440-22-4	1.289	1.05	1.05	10510	10510	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		92		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	copper	7440-50-8	11.320	9.23	9.24	92268	92388	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		182		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	copper	7440-50-8	22.292	18.17	18.20	181696	181933	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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